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AMENDMENT TO THE SPECIFICATION

Please replace the paragraph from page 9, line 28 to page 10, line 20.

Moreover, a driver, such as an ASIC (Application Specific Integrated Circuit) chip and peripheral IC components, can be connected to the panels through a COF (chip on flex) packaging method. The feature of the first embodiment of the present invention is to provide one ASIC chip 364 shared between the primary-display panel module 300M and the secondarydisplay panel module 300S. Thus, the ASIC chip 364 and the peripheral IC components are formed in relation to a connector that electrically connects the primary and secondary panels, therefore facilitating coupling the ASIC to the first and second display panels. The connector can be substantially flexible, such as a FPCB (flexible printed circuit board) 362, which in and by itself inherently does not have any switches within the flexible printed circuit board, such that the flexible printed circuit board is independent of any switches, as shown in the embodiment of FIG 4. The two ends of the FPCB 362 are connected to the glass substrates of the first LCD panel 340 and the second LCD panel 350, respectively. The ASIC (Application Specific Integrated Circuit) is an IC product created in accordance with user-defined circuit design, which integrates multiple traditional-chip circuits on a chip to substantially reduce product defect rates. Currently, various kinds of ASIC chips have been developed, including an image/drafting chip, an LCD panel control chip, and an LCD display control chip.

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